

STPS40L40CT/CW

LOW DROP POWER SCHOTTKY RECTIFIER

MAIN PRODUCTS CHARACTERISTICS

I _{F(AV)}	2 x 20 A
V_{RRM}	40 V
Tj (max)	150 °C
V _F (max)	0.49 V

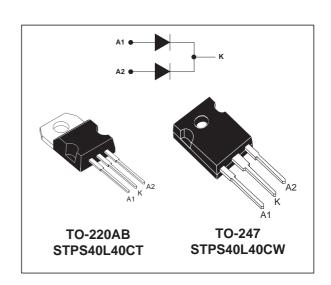
FEATURES AND BENEFITS

- LOW FORWARD VOLTAGE DROP MEANING VERY SMALL CONDUCTION LOSSES
- LOW DYNAMIC LOSSES AS A RESULT OF THE SCHOTTKY BARRIER
- AVALANCHE CAPABILITY SPECIFIED



Dual center tap Schottky barrier rectifier designed for high frequency Switched Mode Power Supplies and DC to DC converters.

Packaged in TO-220AB and TO-247 this device is intended for use in low voltage, high frequency inverters, free-wheeling and polarity protection applications.



ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			40	V
I _{F(RMS)}	RMS forward current			30	А
I _{F(AV)}	Average forward current	forward current Tc = 130°C Per diode		20	А
	δ = 0.5 Per dev		Per device	40	
I _{FSM}	Surge non repetitive forward current	tp = 10 ms S	inusoidal	230	Α
I _{RRM}	Repetitive peak reverse current	tp = 2 µs squ	uare F = 1kHz	2	Α
I _{RSM}	Non repetitive peak reverse current	tp = 100 μs :	square	3	А
P _{ARM}	Repetitive peak avalanche power	tp = 1µs Tj	= 25°C	8100	W
T _{stg}	Storage temperature range			- 65 to + 150	°C
Tj	Maximum operating junction temperature *			150	°C
dV/dt	Critical rate of rise of reverse voltage			10000	V/µs

^{* :} $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ thermal runaway condition for a diode on its own heatsink

July 2003 - Ed: 7A

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THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
R _{th (j-c)}	Junction to case	Per diode	1.5	°C/W
		Total	0.8	
R _{th(c)}		Coupling	0.1	°C/W

When the diodes 1 and 2 are used simultaneously:

 Δ Tj(diode 1) = P(diode1) x R_{th(j-c)}(Per diode) + P(diode 2) x R_{th(c)}

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests Conditions		Min.	Тур.	Max.	Unit
I _R *	Reverse leakage current	Tj = 25°C	$V_R = V_{RRM}$			0.8	mA
		Tj = 100°C			30	70	mA
V _F *	Forward voltage drop	Tj = 25°C	I _F = 20 A			0.53	V
		Tj = 125°C	I _F = 20 A		0.42	0.49	
		Tj = 25°C	I _F = 40 A			0.69	
		Tj = 125°C	I _F = 40 A		0.6	0.7	

Pulse test : * tp = 380 μ s, δ < 2%

To evaluate the conduction losses use the following equation : $P = 0.28 \text{ x } I_{F(AV)} + 0.0105 I_{F}^{2}_{(RMS)}$

Fig. 1: Average forward power dissipation versus average forward current (per diode).

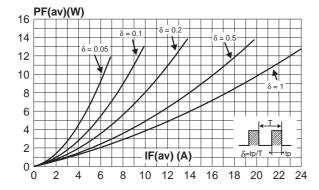


Fig. 3: Normalized avalanche power derating versus pulse duration.

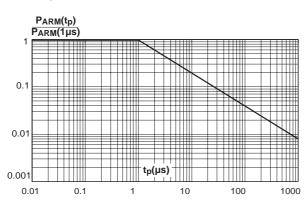


Fig. 2: Average current versus ambient temperature ($\delta = 0.5$, per diode).

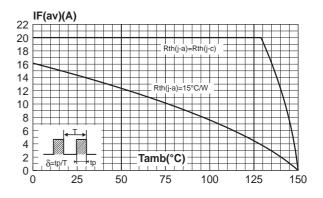


Fig. 4: Normalized avalanche power derating versus junction temperature.

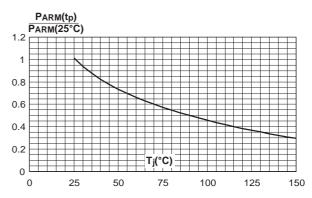


Fig. 5: Non repetitive surge peak forward current versus overload duration (maximum values, per diode).

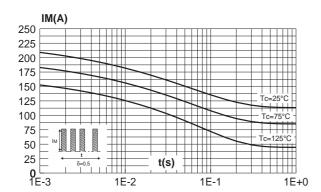


Fig. 6: Relative variation of thermal impedance junction to case versus pulse duration.

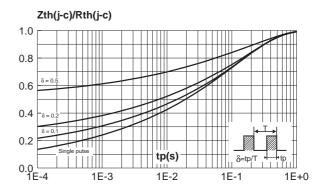


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values, per diode).

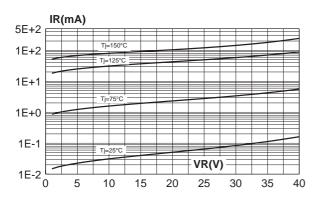


Fig. 8: Junction capacitance versus reverse voltage applied (typical values, per diode).

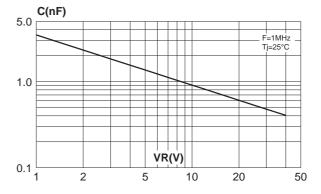
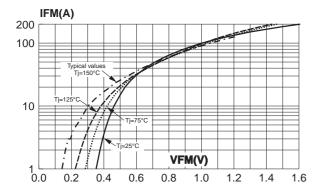


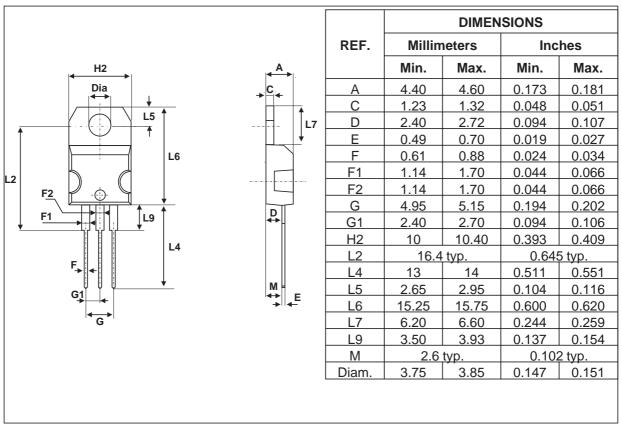
Fig. 9: Forward voltage drop versus forward current (maximum values, per diode).



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PACKAGE MECHANICAL DATA

TO-220AB



COOLING METHOD : C

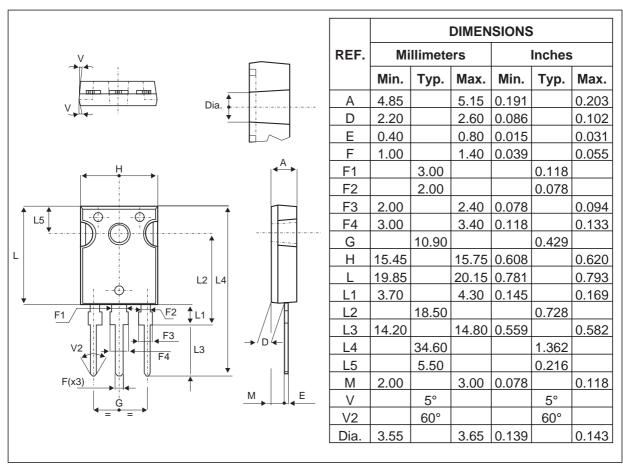
■ RECOMMENDED TORQUE VALUE: 0.55M.N

■ MAXIMUM TORQUE VALUE: 0.70 M.N

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PACKAGE MECHANICAL DATA

TO-247



COOLING METHOD : C

■ RECOMMENDED TORQUE VALUE: 0.8M.N

MAXIMUM TORQUE VALUE: 1.0M.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS40L40CT	STPS40L40CT	TO-220AB	2g	50	Tube
STPS40L40CW	STPS40L40CW	TO-247	4.4g	30	Tube

■ EPOXY MEETS UL94,V0

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